

**Product Summary**

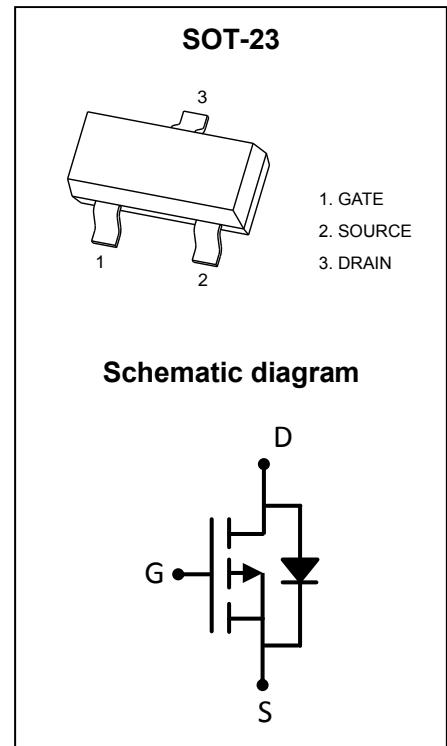
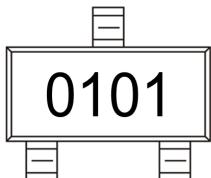
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-100V	580mΩ@-10V	-1A
	650mΩ@-4.5V	

**Feature**

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- AEC-Q101 qualified (Automotive grade with suffix " Q" .)
- Expsemi technology

**Application**

- Load Switch
- DC/DC Converter

**MARKING****ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain - Source Voltage	$V_{DS}$	-100	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1,4</sup>	$I_D$	-1.0	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	-4.0	A
Power Dissipation <sup>4,5</sup>	$P_D$	0.77	W
Thermal Resistance from Junction to Ambient <sup>5</sup>	$R_{\theta JA}$	162	°C/W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55~+150	°C

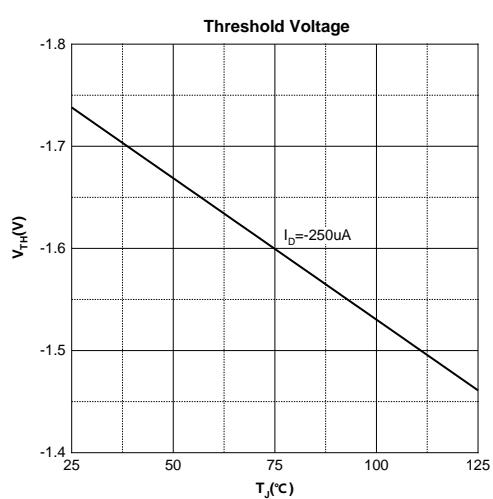
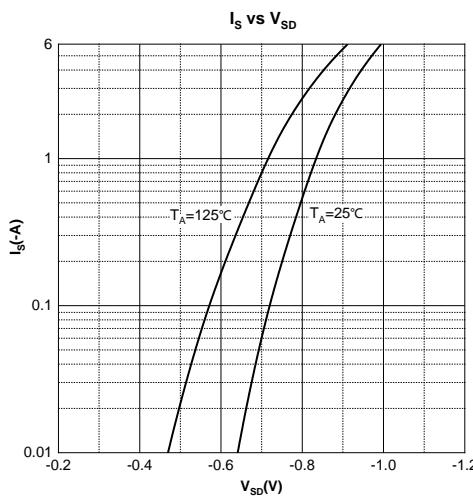
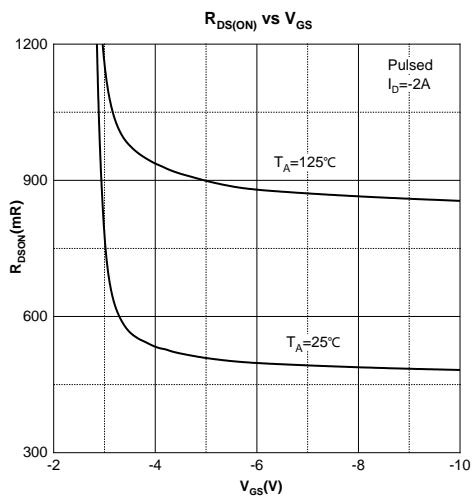
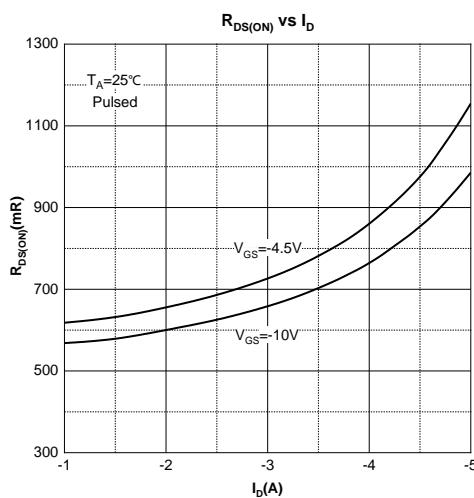
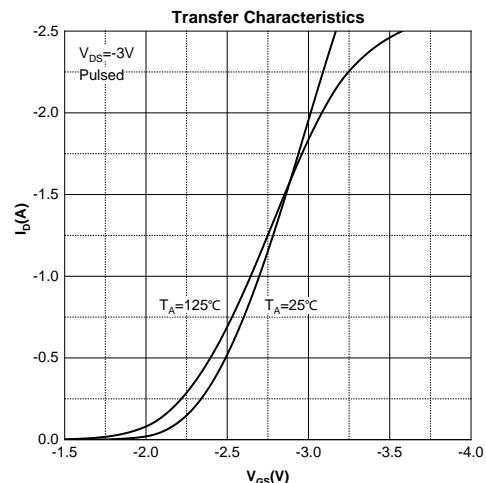
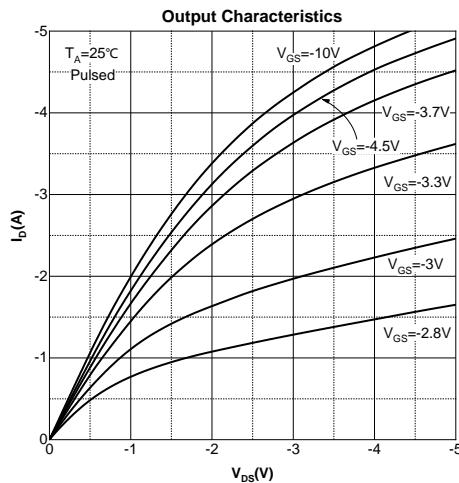
**MOSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-100			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = -80\text{V}, V_{\text{GS}} = 0\text{V}$			-1	$\mu\text{A}$
Gate - Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			$\pm 100$	nA
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.5	-2.2	-3.0	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -1\text{A}$		580	800	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -0.5\text{A}$		650	1000	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = -45\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		300		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			20		
Reverse Transfer Capacitance	$C_{\text{rss}}$			17		
Gate Resistance	$R_g$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		4.6		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = -10\text{V}, I_D = -1\text{A}$		3.2		$\text{nC}$
Gate-source Charge	$Q_{\text{gs}}$			0.5		
Gate-drain Charge	$Q_{\text{gd}}$			1.1		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -10\text{V}, V_{\text{GS}} = -10\text{V}, I_D = -1\text{A}, R_G = 2.5\Omega$		10		$\text{ns}$
Turn-on Rise Time	$t_r$			32		
Turn-off Delay Time	$t_{\text{d}(\text{off})}$			28		
Turn-off Fall Time	$t_f$			9		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_s = -1.0\text{A}$			-1.2	V

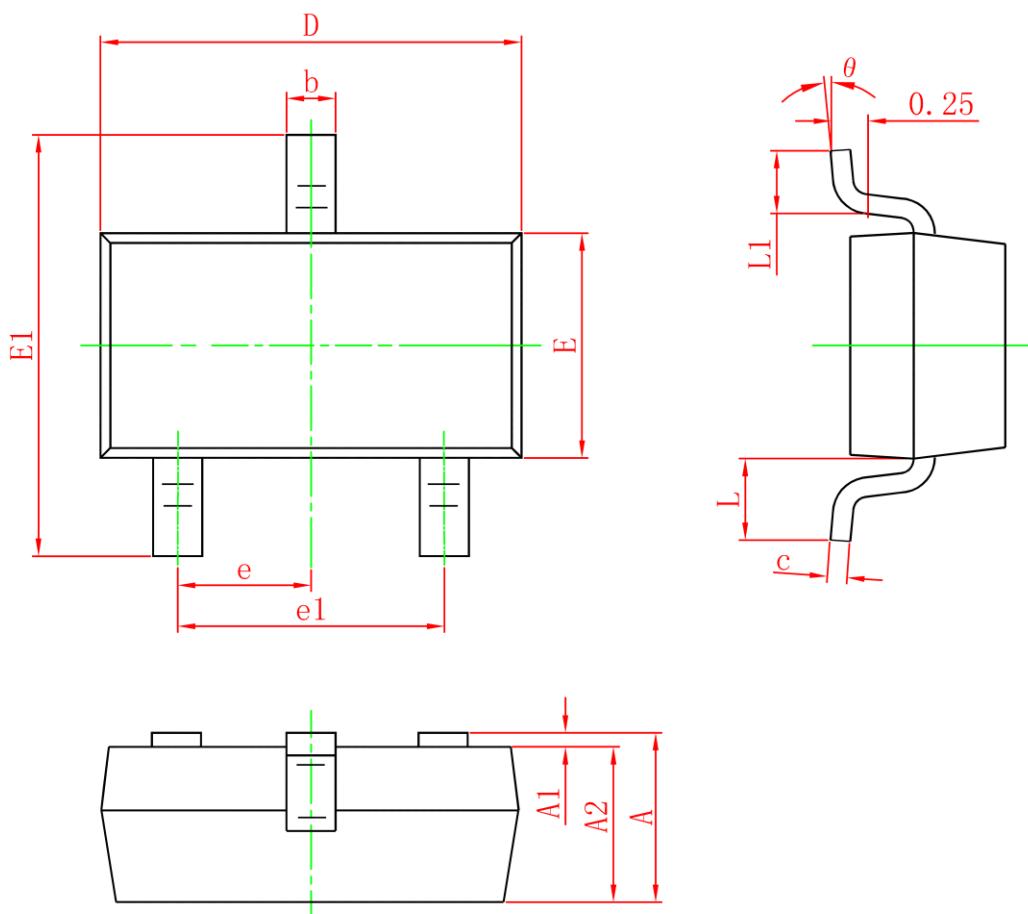
Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width  $\leq 10\mu\text{s}$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .
- 5.Device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## Typical Characteristics



## SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0	0.100	0	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.150	1.500	0.045	0.059
E1	2.250	2.650	0.089	0.104
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°